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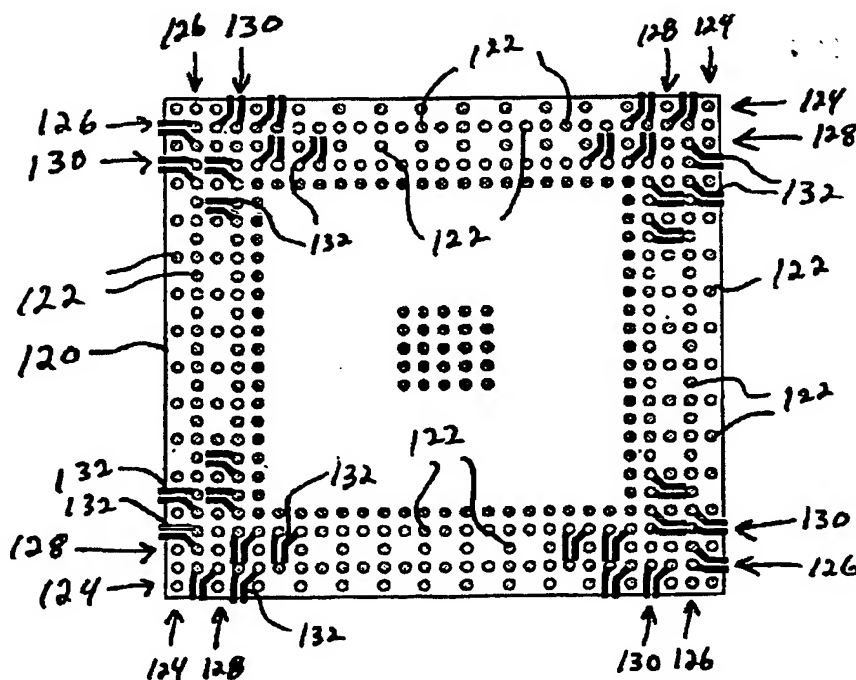
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- (54) Title:** FLIP CHIP DIE BOND PADS, DIE BOND PAD PLACEMENT AND ROUTING OPTIMIZATION



(57) Abstract: An integrated circuit die for a flip chip has circular die bond pads (122). Circular die bond pads allows for a higher density of bond pads when a mating printed circuit board has routing lines between its corresponding pads. In one form, there is provided a flip chip having a die (120) and a plurality of die bond pads (122) situated on the die. Each die bond pad of the die is circular.

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